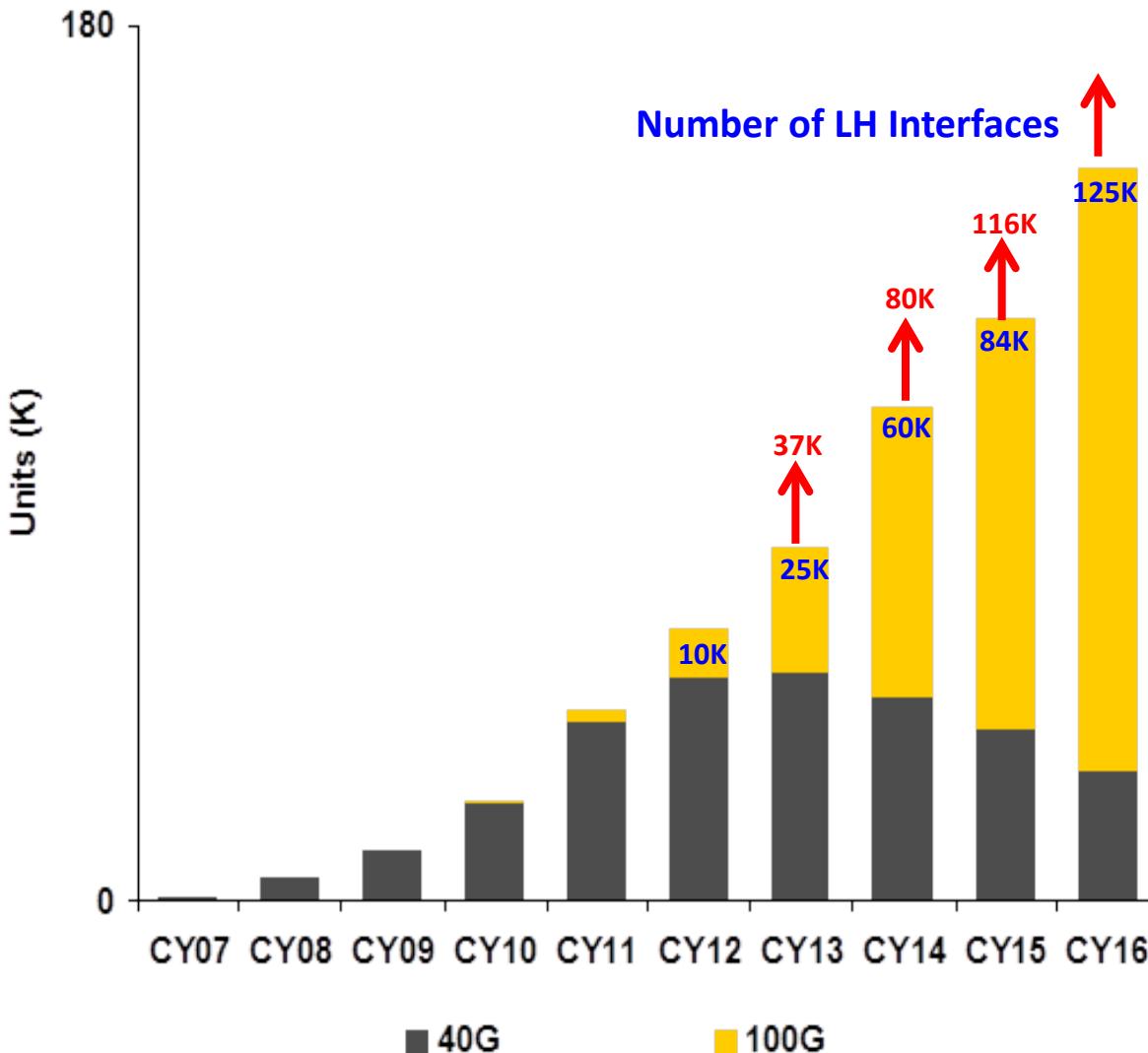

Optical Integration and the Role of DSP in Coherent Optics Modules

Atul Srivastava
CTO, NTT Electronics - America

Outline

- **100G Deployment**
 - Rapid Growth in Long Haul
 - Role of Modules
- **100G Module Standards and their Applications**
 - Gen1 5x7 MSA
 - Gen2 4x5 MSA
 - Pluggable Modules (CFP, CFP2...)
- **Challenges for DSP and Optical Components**
 - Lower Power Dissipation
 - Smaller Size
 - Packaging
- **Discussion**

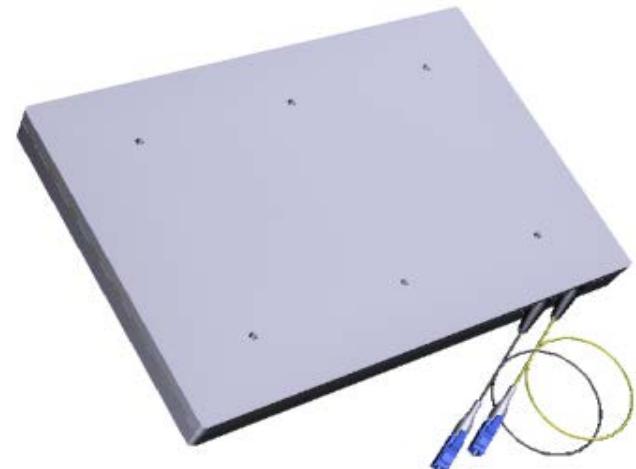
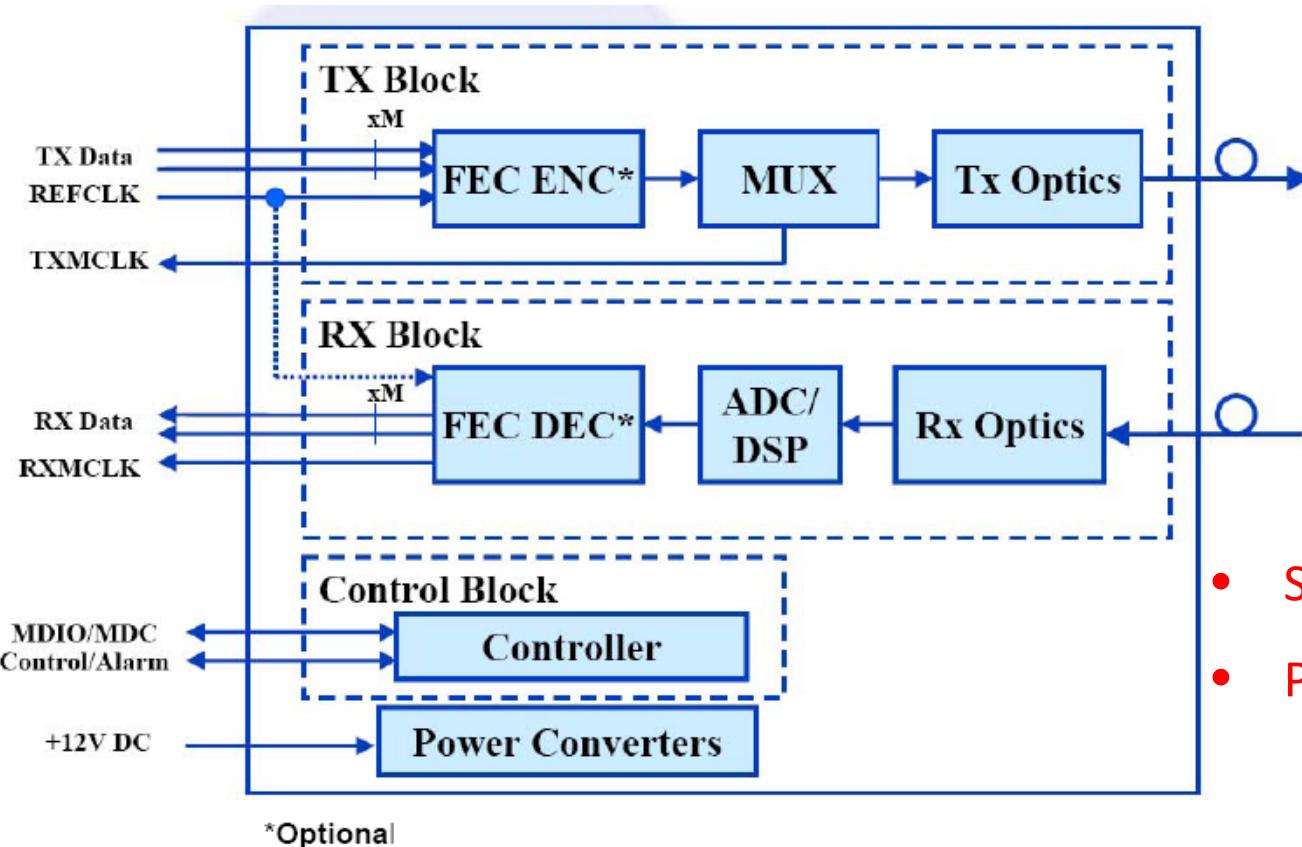
Long Haul 100G Growth



- 2015: >100K LH Interfaces
- Only 15-20% modules

Ref: A. Schmitt, Infonetics, OIF meeting Jan. 2013

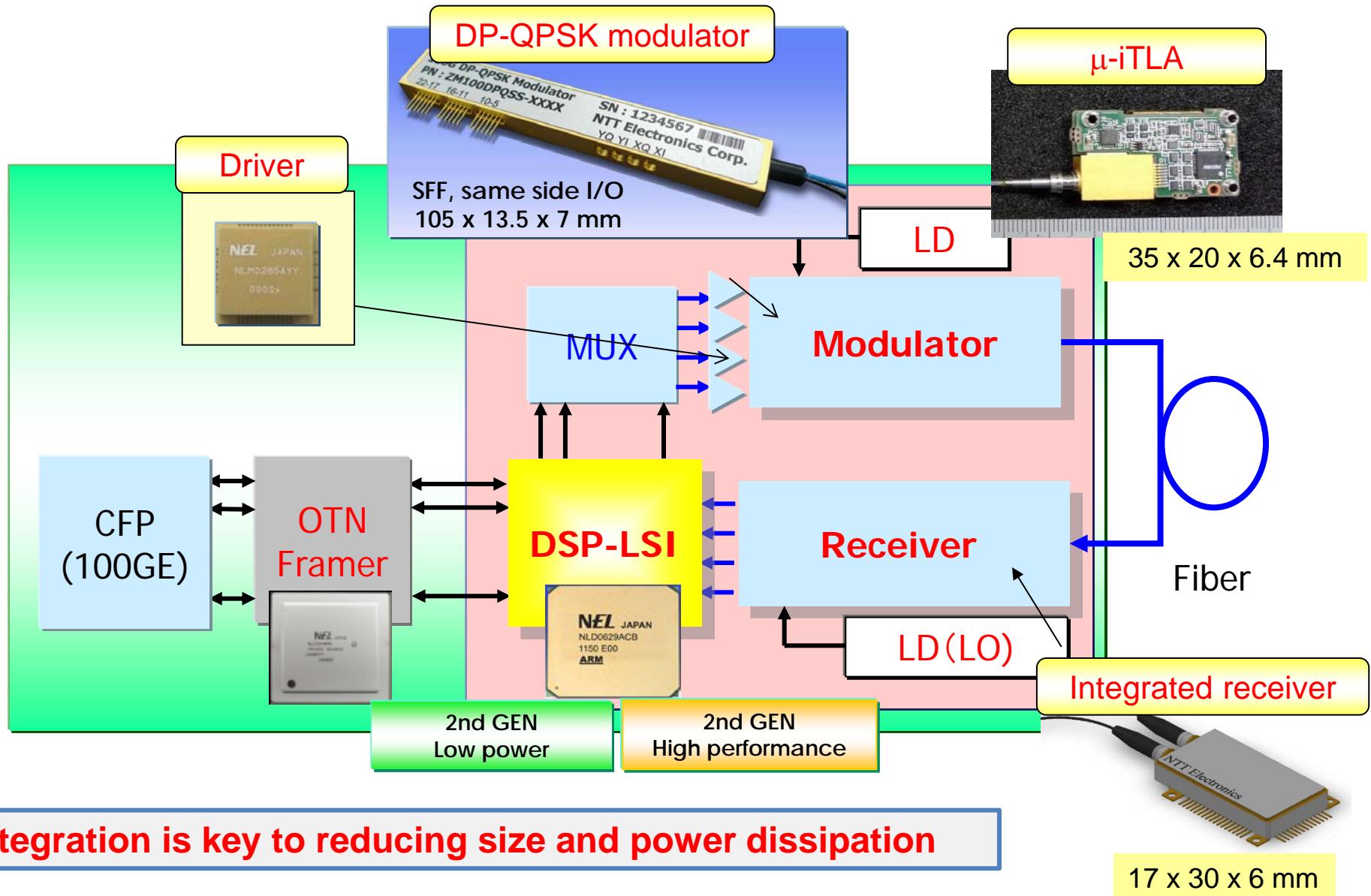
Current OIF LH 100G MSA module:



- Size: 5 in. x 7 in.
- Power Dissipation: 80 W

NEL product lineup for 100G linecard

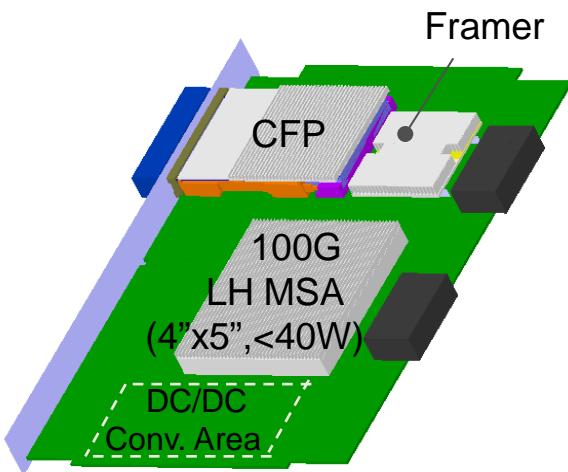
NEL



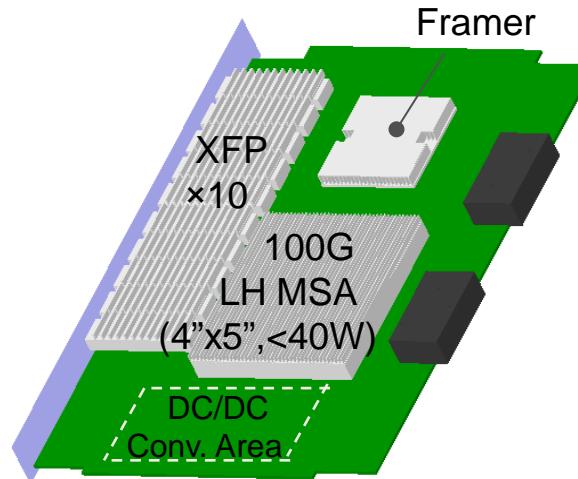
Example of Module Layout in the 100G Transmission Line Card

NEL®

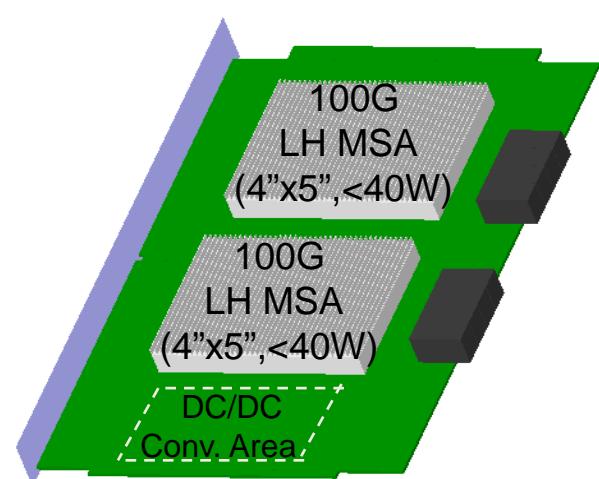
a) Transponder



b) Muxponder



c) Regenerator



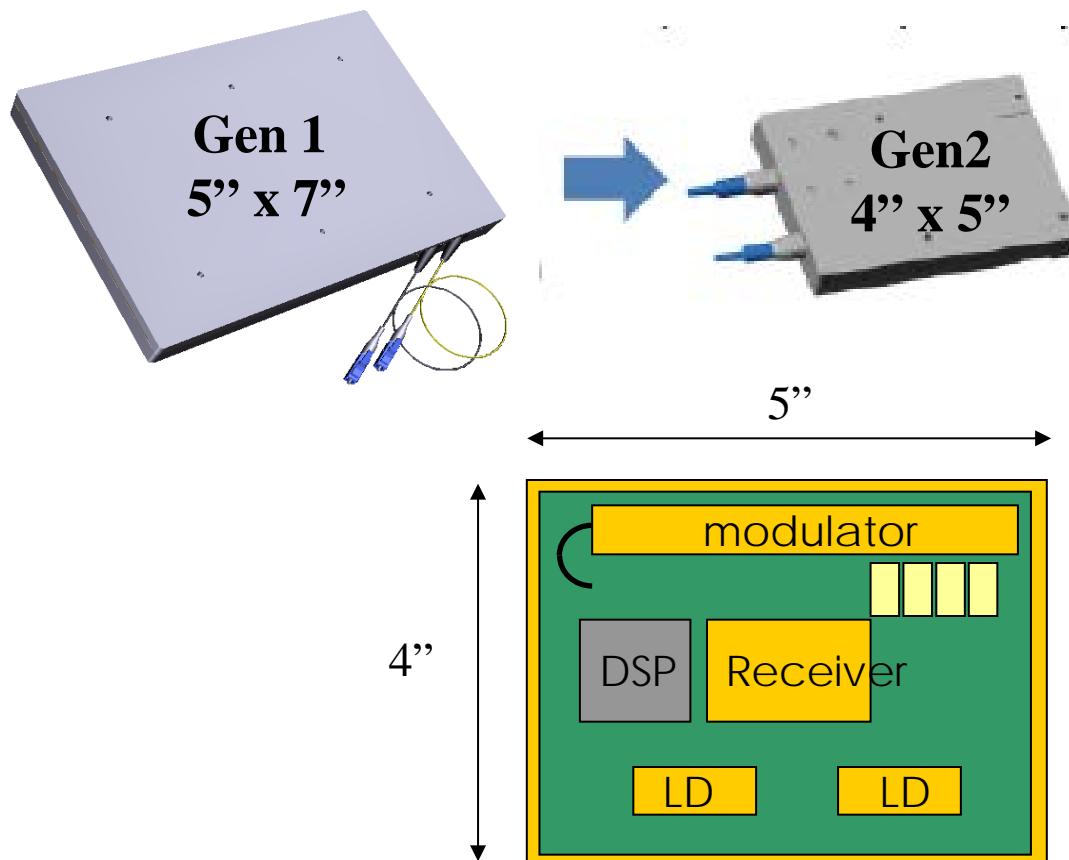
Module size required for the line card

	a) Transponder	b) Muxponder	c) Regenerator
5"x7"(Gen.1)	✓		
4"x5"(Gen.2)	✓	✓	✓

The module with the size of 4"x5" can enable three kinds of the line cards

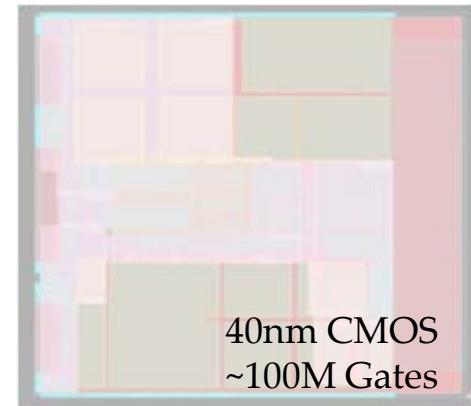
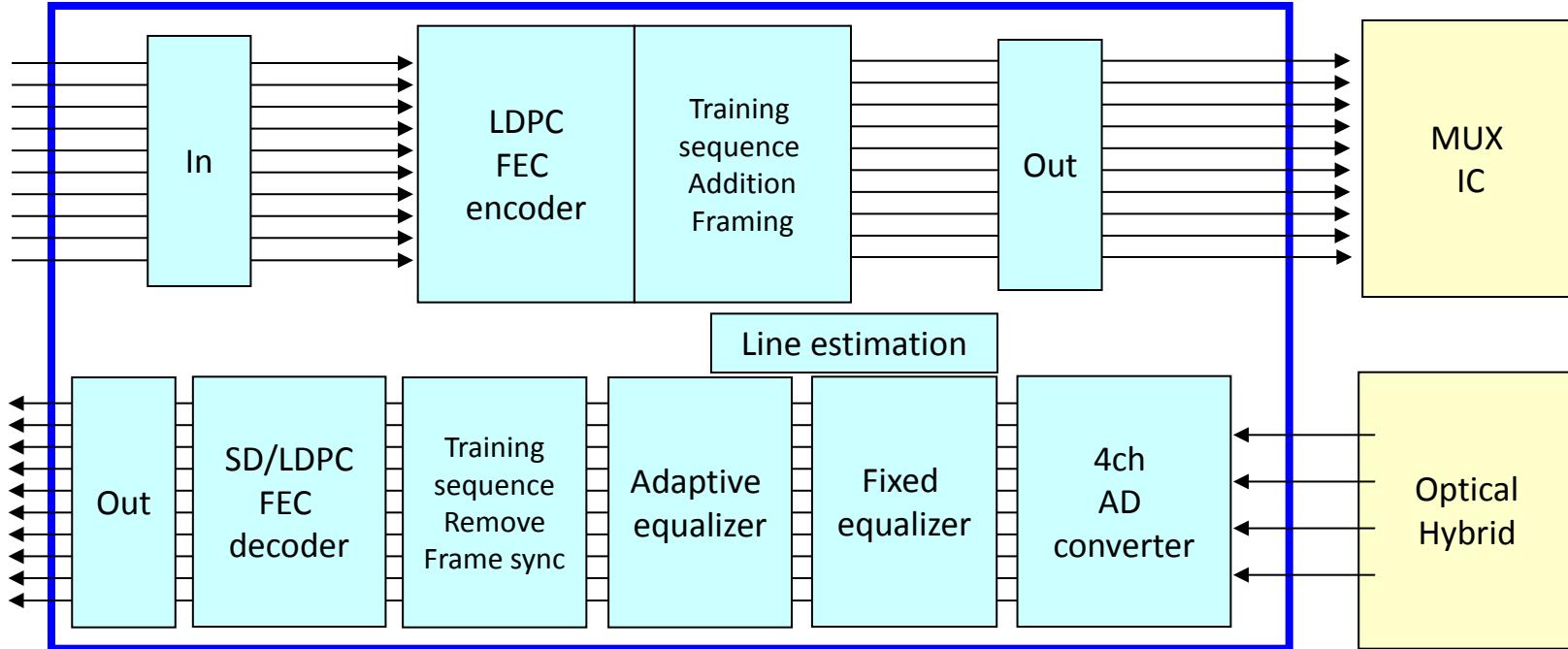
Courtesy: Onaka, Fujitsu

Evolution of 100G modules: LH Applications



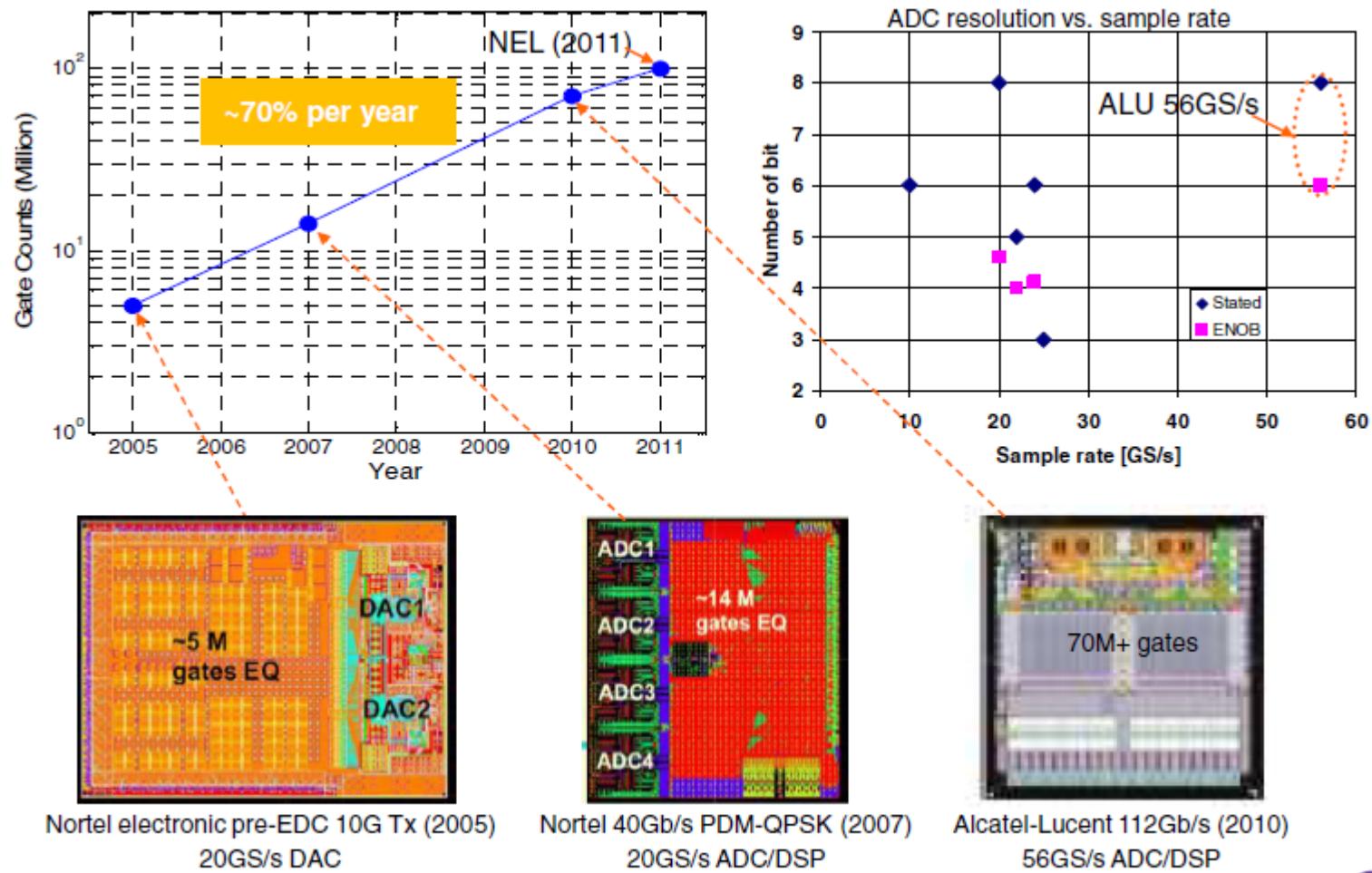
- Module Power dissipation dominated by electronic components such as DSP and MUX
- Module Size (width, depth, height) determined by optical components such as Tx and Rx

Block Diagram of 100G Coherent DSP



DSP ASIC Milestones

NEL®

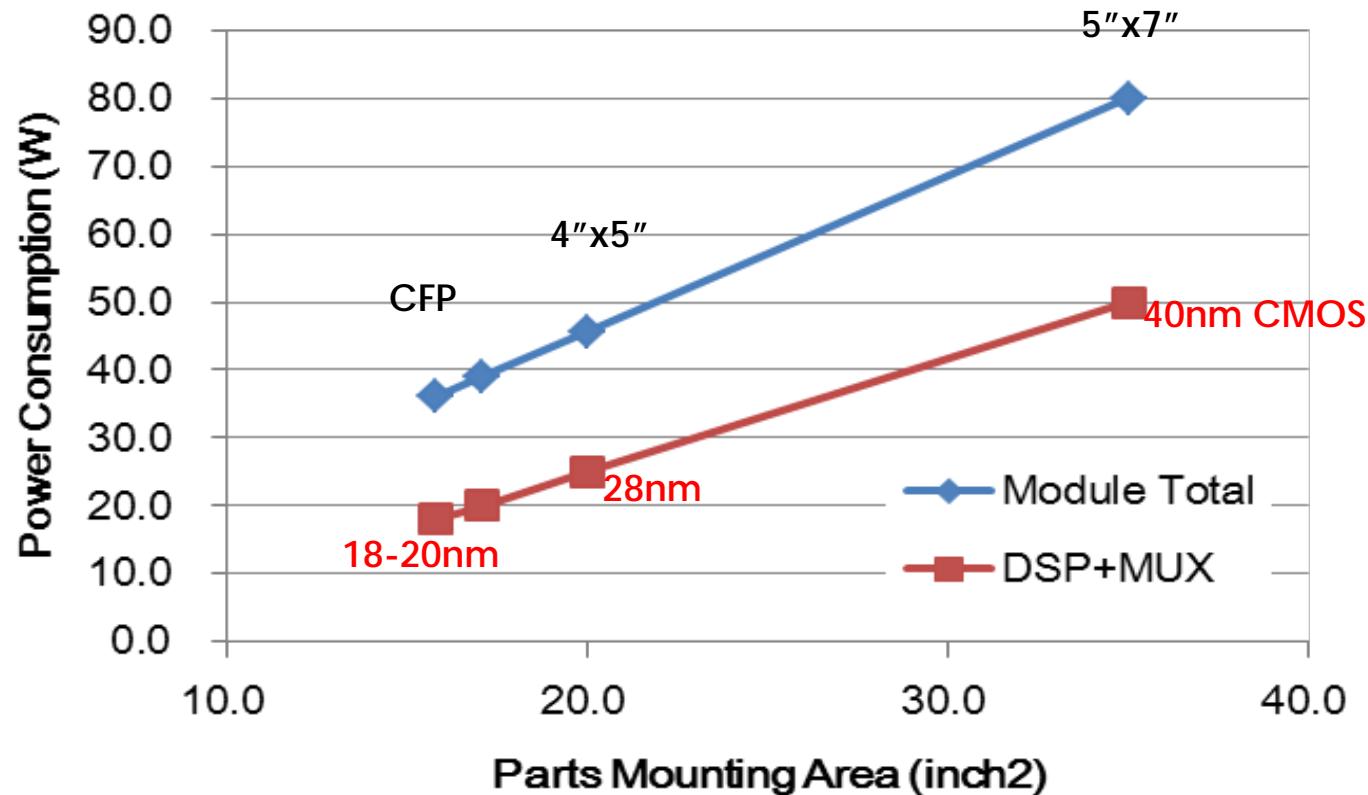


Breakdown of 100G module power dissipation

NEL®

	Gen1 MSA	4"x5" Gen2 MSA
DSP	35.0	20.0
MUX	6.5	0.0
Modulator(TEC)	0	0
Driver	10.0	7.0
ITLA(Tx&LO)	6.0	8.0
Receiver FE	3.5	1.5
MISC	2.0	1.0
DD-conv.	16.0	2.5
Total	79.0 W	40.0 W

100G Transceiver Module/DSP Power Dissipation

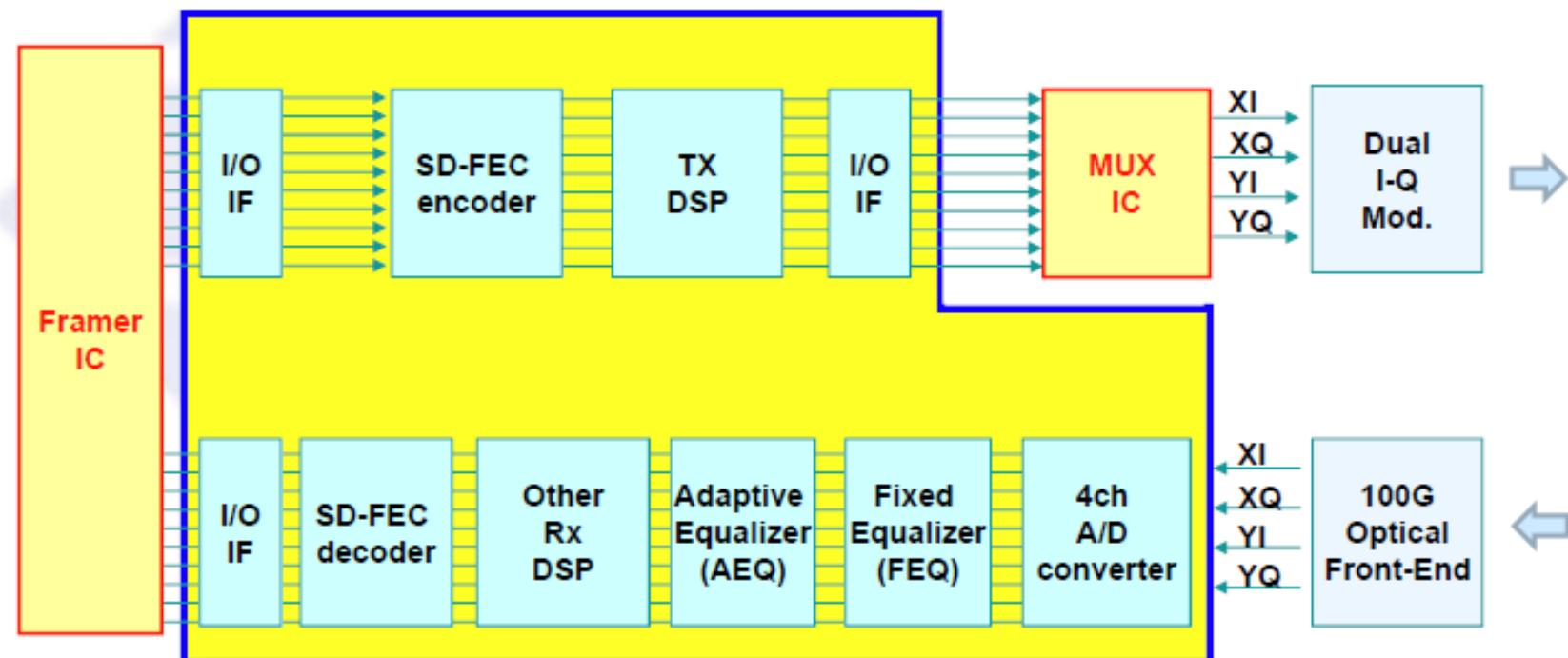


100G Cohernet DSP ASIC Gen -1

NEL®

- 40nm CMOS with External Functions

- External Framer ASIC
- External Transmit Mux

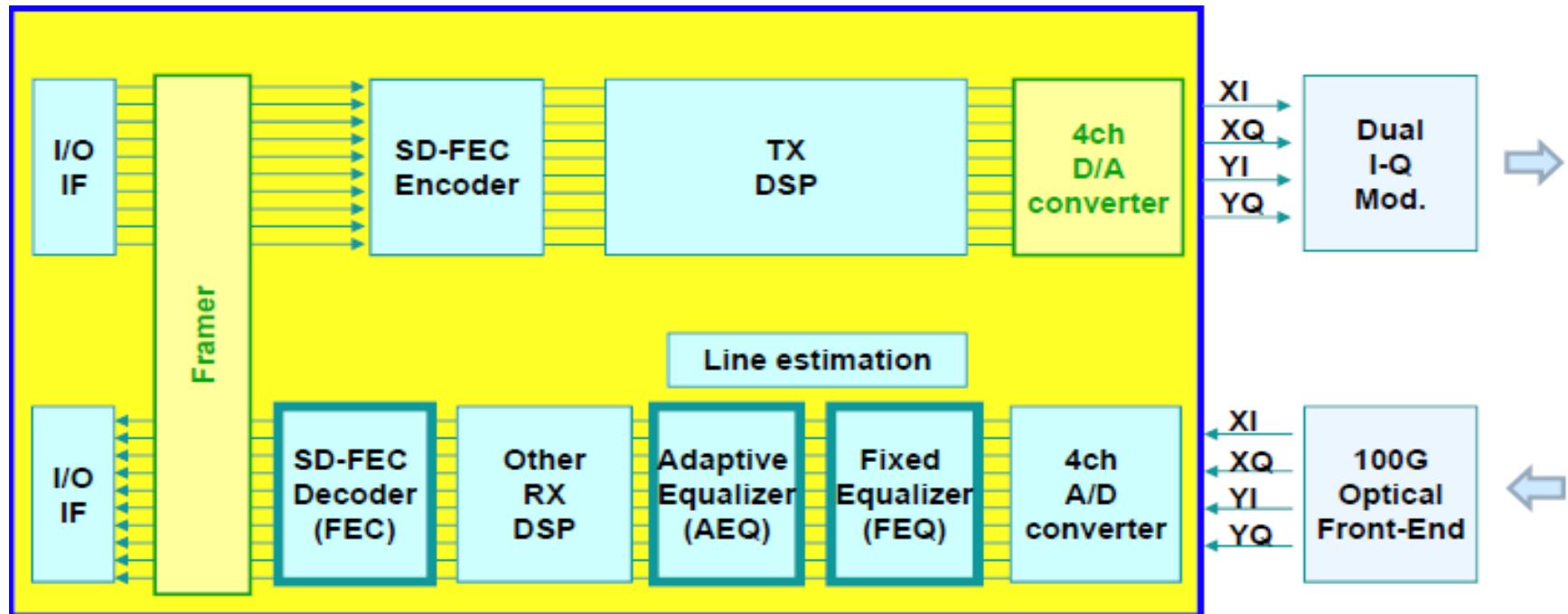


100G Cohernet DSP ASIC Gen -2

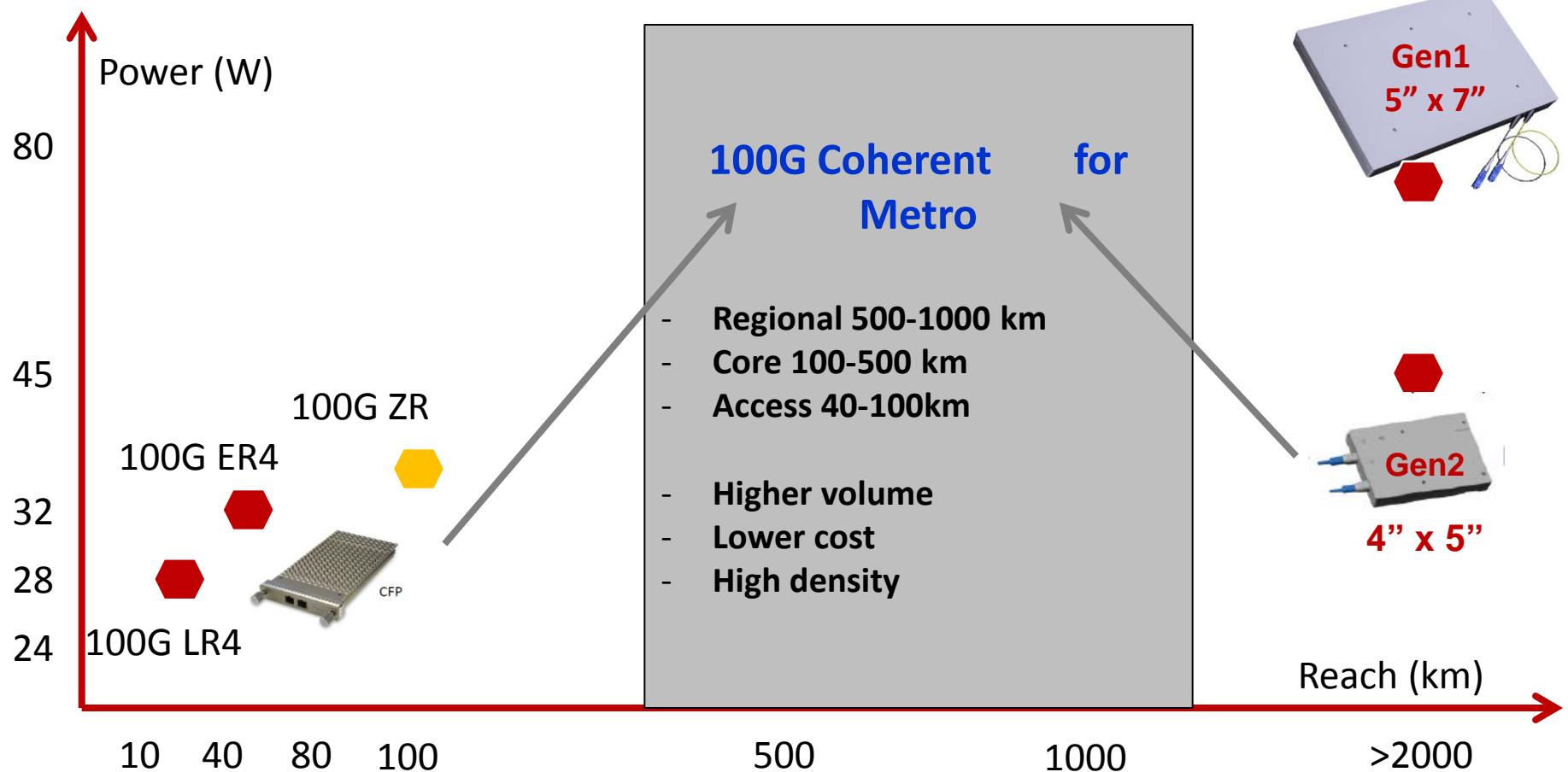
NEL®

- Next Gen CMOS with Additional Functionality

- Internal Framer
- Internal 4x DAC

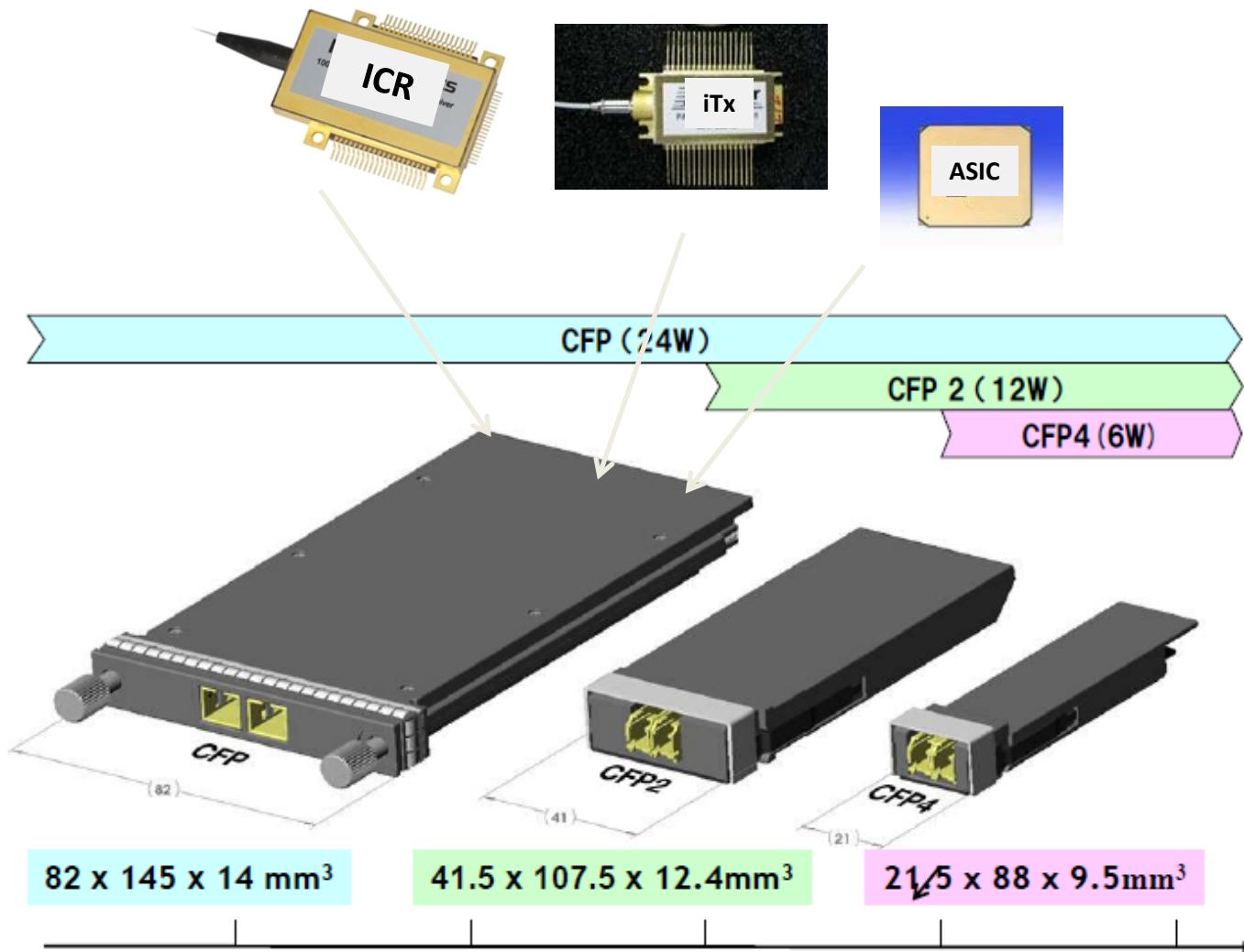


100G Transceiver Module Landscape



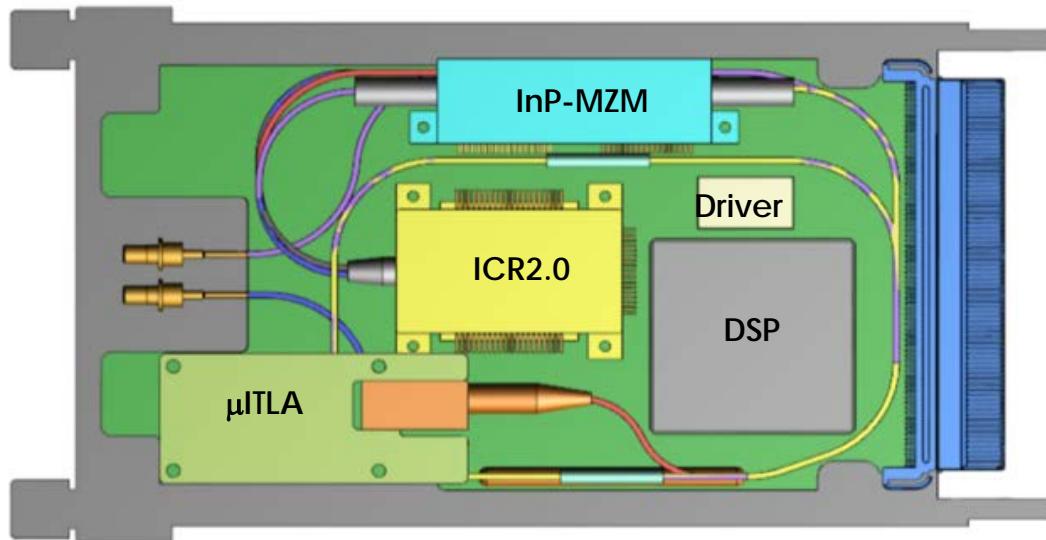
Integrated Components for smaller pluggable modules

NEL®



Integrated Components for Coherent CFP module

Size 82 x 145 x 14 mm

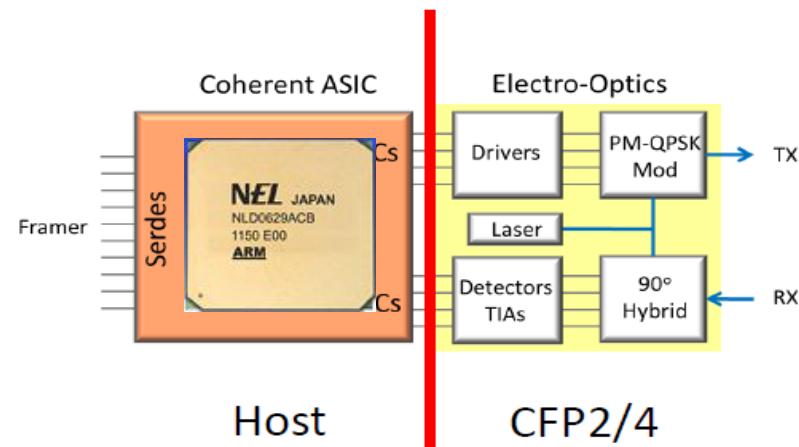


Power dissipation 24 W

	CFP target
DSP	12.0
MUX	0
Modulator(TEC)	1.0
Driver	3.0
ITLA(Tx&LO)	4.0
Receiver FE	1.5
MISC	1.0
DD-conv.	1.5
Total	24.0 W

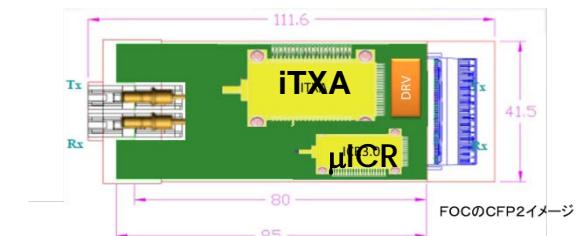
100G CFP2 Analog Coherent Optics module

NEL



DSP on Host Board

CFP2 ACO



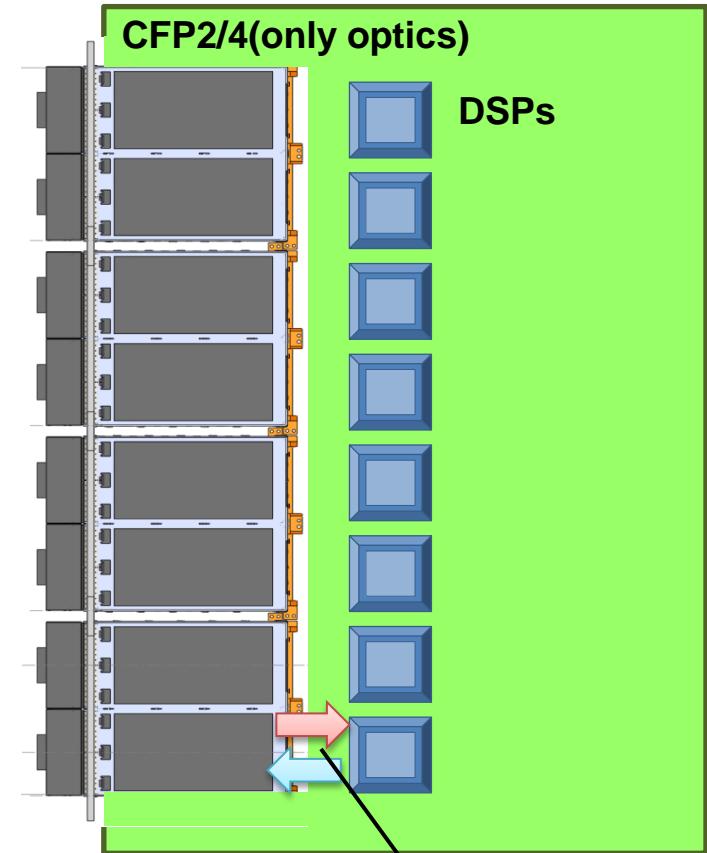
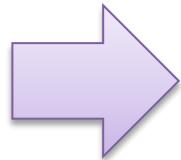
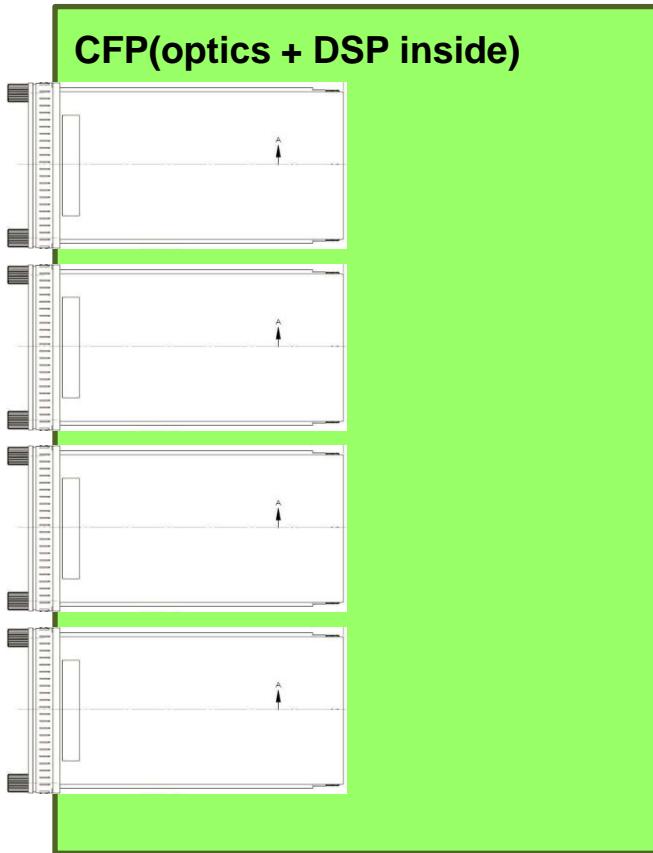
Size: 42 x 106 x 12 mm

Power 12W

CFP2 ACO IA currently under discussion in OIF

Pluggable Digital Coherent TRx

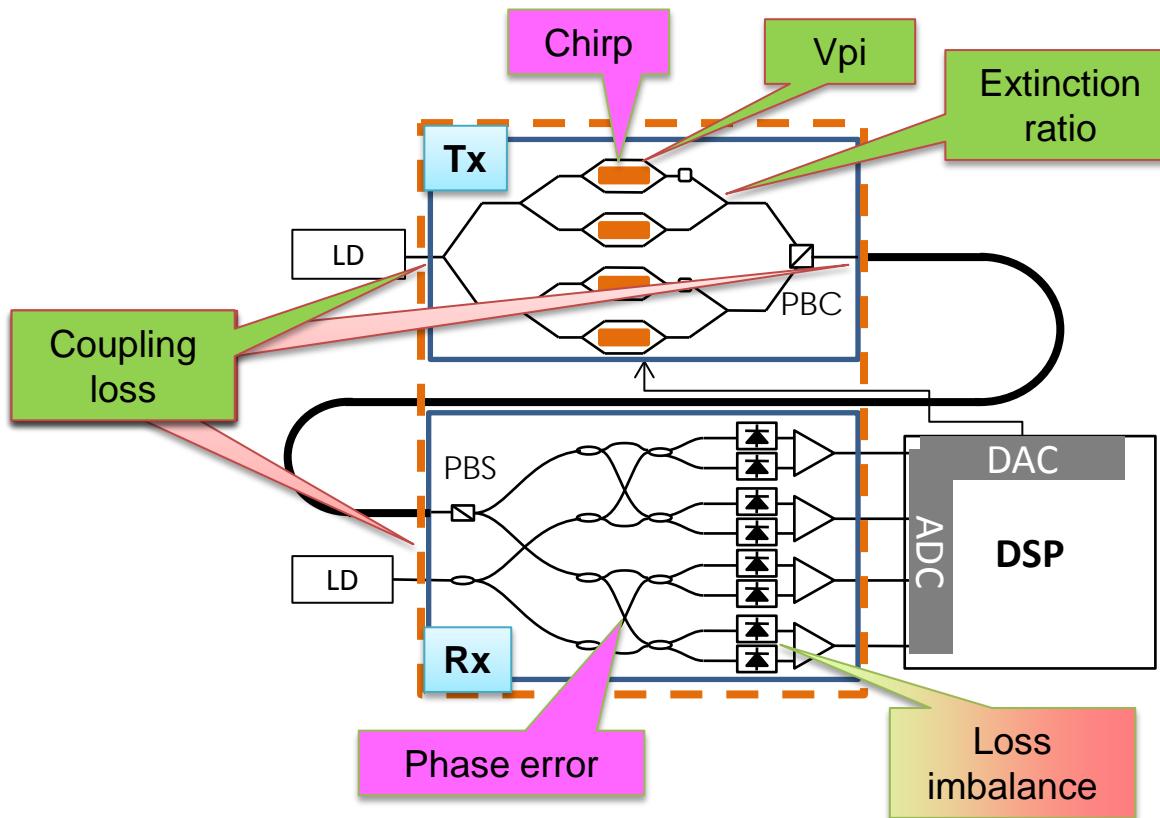
Line card



CFP2: 8 modules/card
CFP4: 16 modules/card

- Optics part will be separated from DSP
- CFP2 will be no more than single optical component

Compact Optical Tx and Rx ...DSP Assist



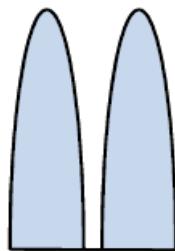
Future Higher Performance DSP-ASICs

- Higher FEC
- Non-linear Compensation
- Cycle Slip Control

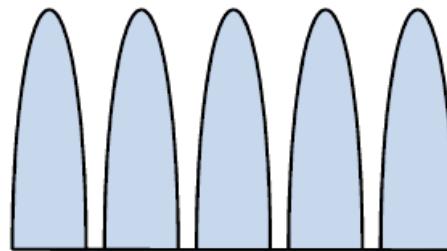
Performance enhancement by DSP

Multi carrier options for 400G and 1T systems

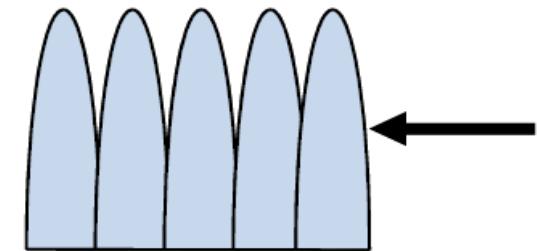
- Dual carrier 2x200G for 400G switching to DP- 16QAM
- Additional carriers can be added to make a 4 X 100G, or 10 X 100G, or 5 X 200G superchannel



2 X 200G Channels
@ 50GHz

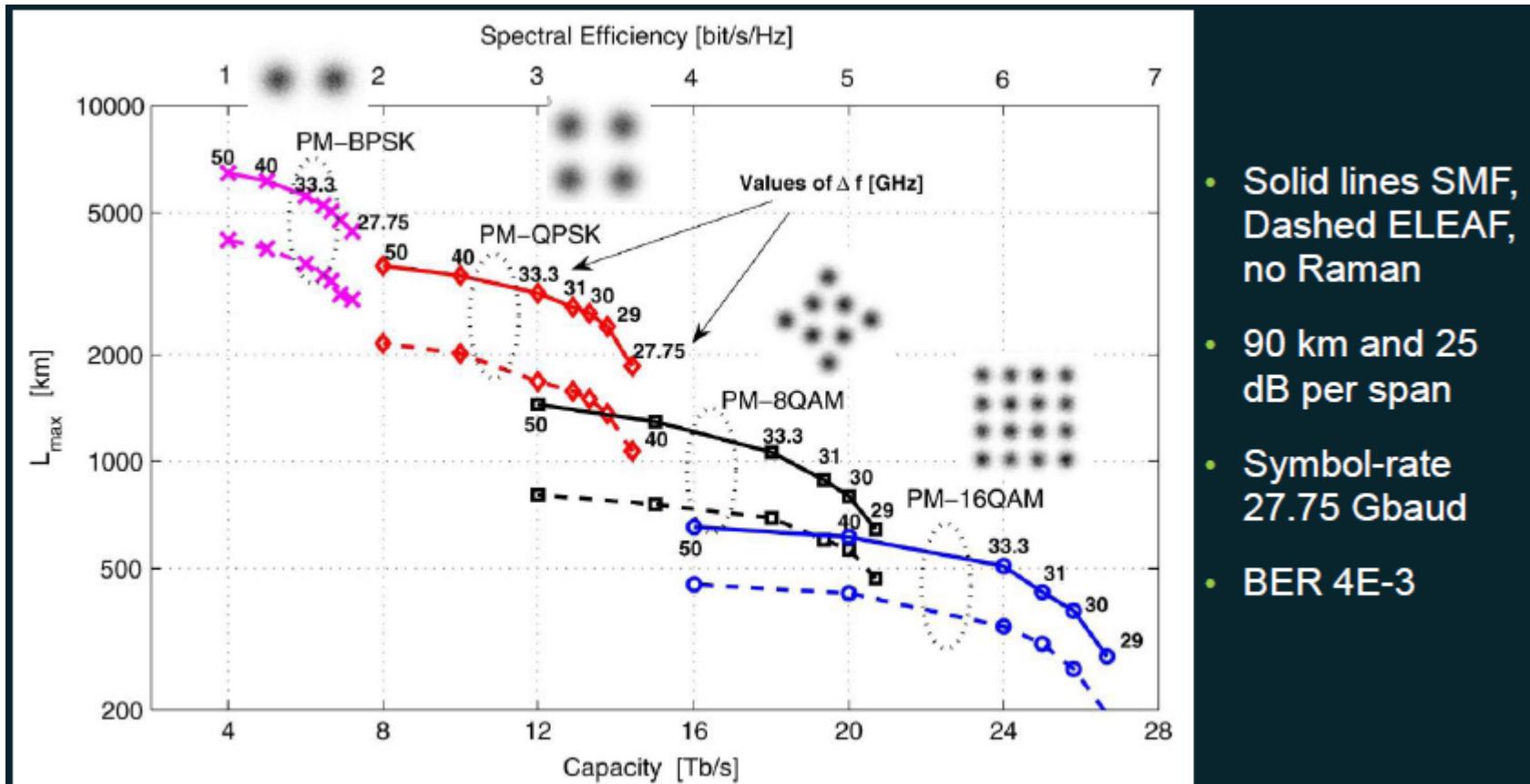


5 X 200G Channels @
50GHz



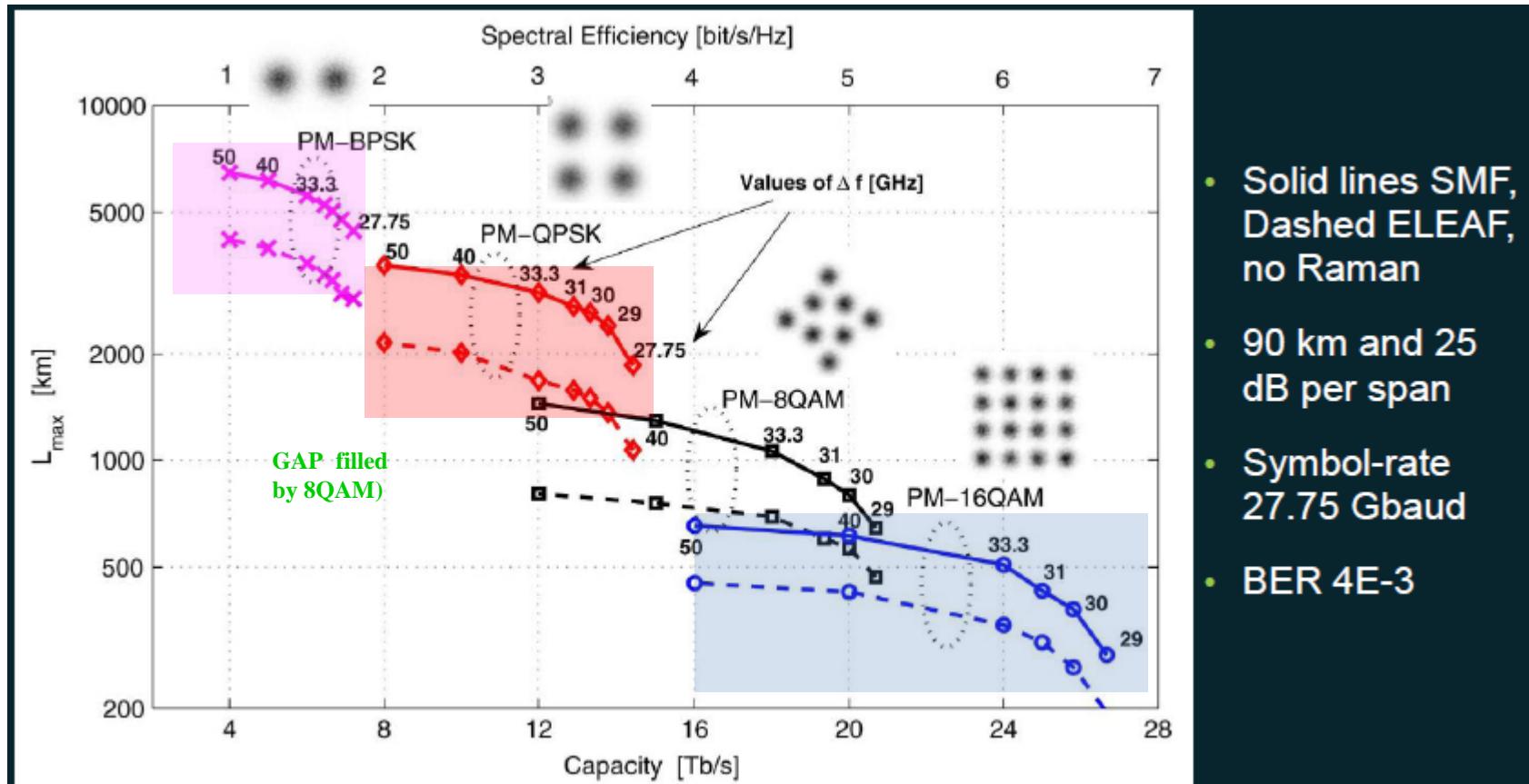
1T Superchannel with
Flexgrid

Reach and Capacity Tradeoff



G. Bosco et al., JLT, vol.29, No.1, p.53, 2011

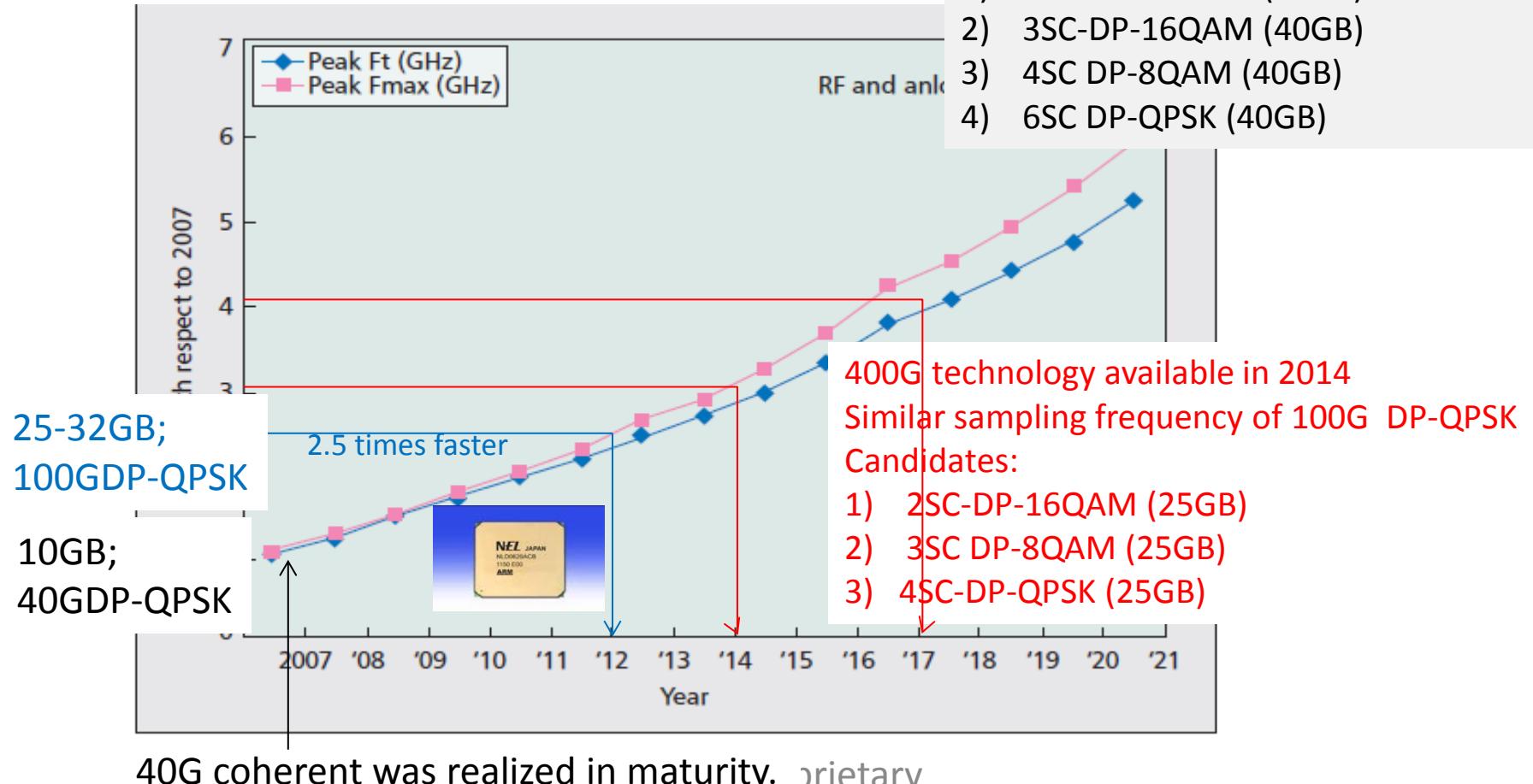
Reach and Capacity Tradeoff



G. Bosco et al., JLT, vol.29, No.1, p.53, 2011

ADC in CMOS for 400G and 1T

International Technology Roadmap for Semiconductors



Thank You !!

Questions?